



Features

- Small Size Standard 16 Pin SOIC or DIP Package
- 0.01% Servo Linearity
- 5300 VAC Peak Input/Output Isolation Available
- Bandwidth $\geq 40\text{kHz}$
- Machine Insertable, Wave Solderable
- Wide Power Supply Range $\pm 18\text{V}$
- Low Supply Current

Applications

- Isolated 4-20mA Converter
- Medical Sensor Isolation
- Switching Power Supply Feedback Circuits
- Isolated Temperature/Pressure Sensors
- Data Acquisition Equipment
- Isolated Motor Controls

Description

The LIA100 and LIA101 are linear isolation amplifiers that integrate a linear optocoupler with two op amps in a single package. They are available in a 16 Pin SOIC or DIP package.

Approvals

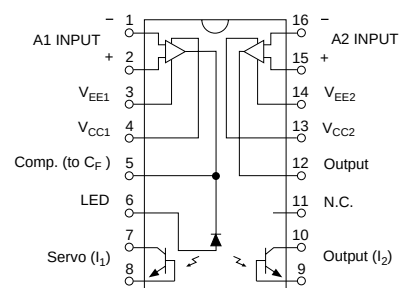
- UL Recognized: File Number E76270
- CSA Certified: File Number LR 43639-10
- BSI Certified to:
 - BS EN 60950:1992 (BS7002:1992)
Certificate #: 7344
 - BS EN 41003:1993
Certificate #: 7344

Ordering Information

Part #	Description
LIA101	16 Pin DIP (50/Tube)
LIA101P	16 Pin Flatpack (50/Tube)
LIA101PTR	16 Pin Flatpack (1000/Reel)

Pin Configuration

LIA100/LIA101 Pinout



Absolute Maximum Ratings (@ 25° C)

Parameter	Min	Typ	Max	Units
Supply Voltages	± 5	-	±18	V
Differential Input Voltage	-	-	± 30	V
Output Short Circuit Duration	Continuous			-
Total Package Dissipation	-	-	11	W
Isolation Voltage Input to Output	3750	-	-	V _{RMS}
Operational Temperature	-40	-	+85	°C
Storage Temperature	-40	-	+125	°C
Soldering Temperature	-	-	-	-
DIP Package	-	-	+260	°C
Surface Mount Package (10 Seconds Max.)	-	-	+220	°C

¹ Above 25°C Derate Linearly 1.67mW/°C

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this data sheet is not implied. Exposure of the device to the absolute maximum ratings for an extended period may degrade the device and effect its reliability.

Electrical Characteristics @ TA = +25°C and ±VCC = 15VDC (unless otherwise specified)

PARAMETERS	CONDITIONS	MIN	TYP	MAX	UNITS
Isolation					
Continuous Voltage, AC	-	-	-	3750	V _{RMS}
Input to Output Leakage Current	1000V _{RMS} ¹ , 60Hz	-	0.2	-	μA _{RMS}
Offset Voltage					
Output Offset Voltage (VOS)	R _F =R _{IN} =51KΩ, K3=1.000 Input Grounded T _A =25°C	-	50	-	mV
Amplifier Input Impedance	-	-	10 ¹² 3	-	Ω pF
ΔVOS/ΔT Average TC of Input Offset Voltage	R _S =50Ω	-	5	-	μV/°C
(Input and Output Stage)					
Common Mode Rejection Ratio, CMRR	60Hz, R _F =1MΩ R _{IN} =10KΩ, Gain=100	-	100	-	dB
Input Offset Voltage	R _S =50Ω, T _A =25°C	-	3	10	mV
Common Mode Range		±12	-	-	V
Frequency Response					
Bandwidth	-	-	40	-	kHz
Slew Rate	0-10V Step Input	-	0.3	-	V/μs
Non-Linearity					
	F _O =300Hz, -10dBm	-	-	0.01	%
Power Supplies					
Input Stage Supply Voltage VCC1, VEE1	-	±5	-	±18	V
Output Stage Supply Voltage VCC2, VEE2	-	±5	-	±18	V
Input (A1) & Output Stage (A2) Supply Current	-	-	5	10	mA
Power Supply Rejection Ratio, PSRR	-	-	80	100	dB

**Electrical Characteristics @ TA = +25°C and
±VCC = 15VDC (unless otherwise specified) (Continued)**

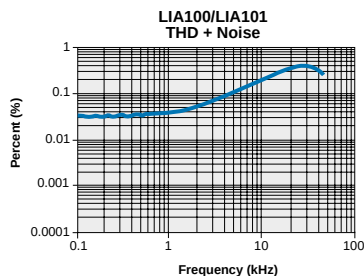
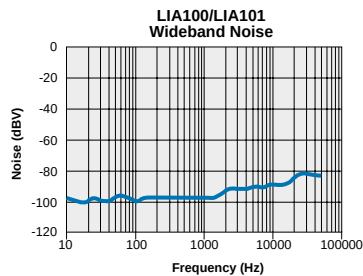
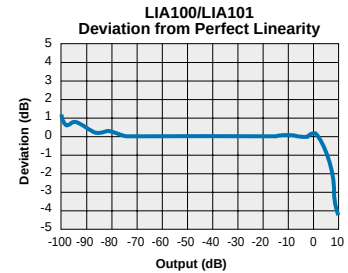
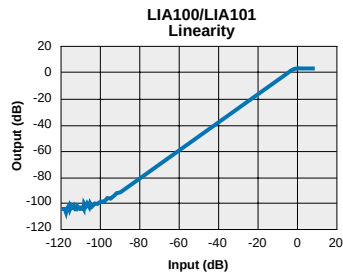
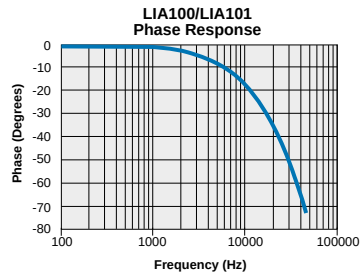
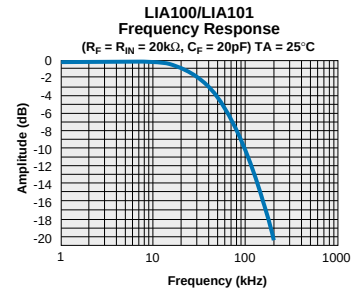
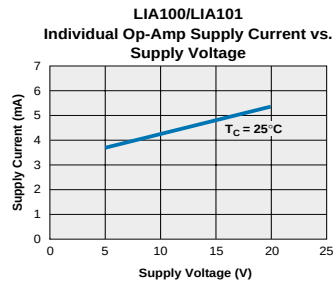
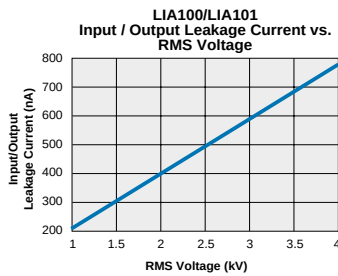
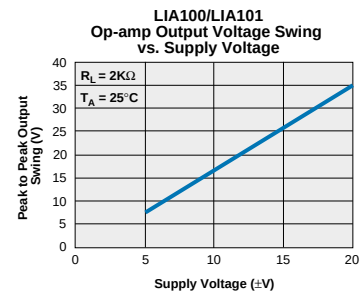
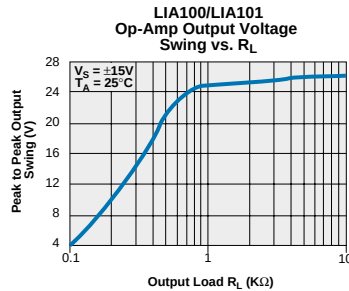
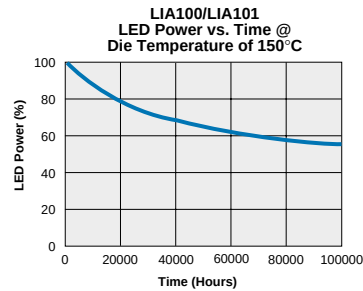
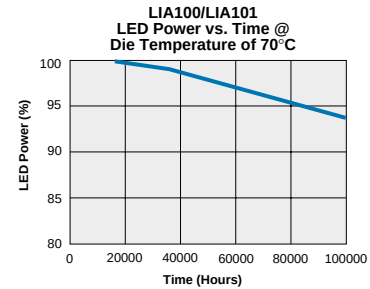
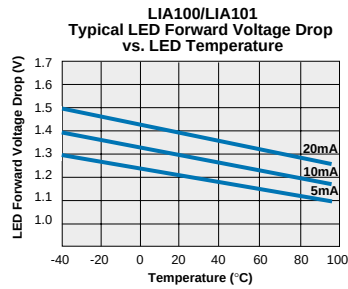
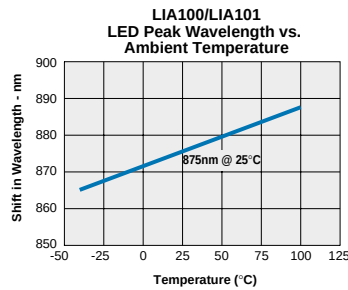
PARAMETERS	CONDITIONS	MIN	TYP	MAX	UNITS
LED Parameters					
Forward LED Current (IF)	-	-	-	20	mA
LED Forward Voltage Drop (VF)	IF=10mA	0.9	1.2	1.4	V
Reverse LED Current	VR=5V	-	-	10	μA
Reverse LED Voltage	-	-	-	5	V
Coupled Characteristics					
K1, Servo Gain (I1/IF)	IF=2-10mA, VCC=15V	0.004	0.008	0.030	
K2, Forward Gain (I2/IF)	IF=2-10mA, VCC=15V	0.004	0.008	0.030	
K3, Transfer Gain (K2/K1)	IF=2-10mA, VCC=15V	0.733	1.000	1.072	
K3, Temperature Coefficient	Over Temperature Range	-	0.005	-	%/°C
Temperature Range					
Operating	-	-40	-	+85	°C
Storage	-	-40	-	+125	°C

K3 Sorted Bins

Bin A = 0.550-0.605
 Bin B = 0.606-0.667
 Bin C = 0.668-0.732
 Bin D = 0.733-0.805
 Bin E = 0.806-0.886
 Bin F = 0.887-0.974
 Bin G = 0.975-1.072
 Bin H = 1.073-1.179
 Bin I = 1.180-1.297
 Bin J = 1.298-1.426

- The LIA101 Series (through hole) is shipped in anti-static tubes of 25 pieces. The LIA100P Series (flatpack) is shipped in anti-static tubes of 50 pieces. Each tube will contain one K3 sorted bin.
- Bin designation marked on each device (A-J).
- Orders for the LIA100/LIA100P product will be shipped using bins available at the date of the order. Any bin (A-J) can be shipped.
- For customers requiring selected bins D E F G we offer part numbers LIA101/LIA101P.

PERFORMANCE DATA*



The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

16 Pin DIP Through Hole (Standard)

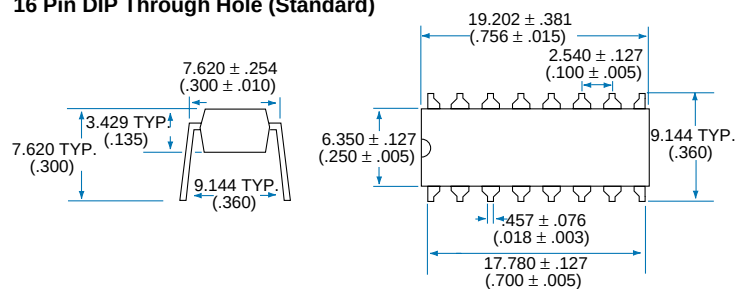


Figure 1: Dimensioned drawing of the test specimen. The drawing shows a rectangular plate with various dimensions and tolerances. The top edge has a diameter of 16.800 DIA. (16.031 DIA.) with a tolerance of $\pm .127$ ($\pm .005$). The bottom edge has a diameter of 2.540 $\pm .127$ (1.00 $\pm .005$). The left edge has a height of 6.350 $\pm .127$ (2.50 $\pm .005$). The right edge has a height of 7.620 $\pm .127$ (3.00 $\pm .005$). The width of the plate is 17.780 $\pm .127$ (7.00 $\pm .005$). The drawing also shows a central vertical line and a horizontal line across the middle.

16 Pin SOIC ("P" Suffix)

The drawing shows the mechanical specifications for a 16 Pin SOIC package. The top view shows a rectangular package with 16 pins (8 on each long side). Key dimensions include: overall width of 10.160 ± .051 (400 ± .002), pin pitch of 1.270 TYP. (.050), pin width of .406 TYP. (.016), and pin length of 8.890 TYP. (.350). The side view shows a maximum height of 2.108 MAX. (.083), a body thickness of 1.016 (.040), and a lead thickness of .254 (.010). The distance from the body to the pin base is 7.493 ± .051 (.295 ± .002).

Dimension	Value
Overall Width	10.160 ± .051 (400 ± .002)
Pin Pitch	1.270 TYP. (.050)
Pin Width	.406 TYP. (.016)
Pin Length	8.890 TYP. (.350)
Maximum Height	2.108 MAX. (.083)
Body Thickness	1.016 (.040)
Lead Thickness	.254 (.010)
Distance from Body to Pin Base	7.493 ± .051 (.295 ± .002)

Figure 1: Dimensions of the Carrier Tape

330.2 DIA. (13.00)

Top Cover Tape Thickness .102 MAX. (.004)

Embossed Carrier

Embossment

6.731 MAX. (.265)

406 MAX. (.016)

12.090 (.476)

1.753 ± .102 (.069 ± .004)

7.493 ± .102 (.295 ± .004)

2.007 ± .102 (.079 ± .004)

1.498 ± .102 (.059 ± .004)

3.987 ± .102 (.157 ± .004)

16.002 ± .305 (.630 ± .012)

10.693 ± .025 (.421 ± .001)

11.989 ± .102 (.472 ± .004)

10.897 ± .025 (.429 ± .001)

1.549 ± .102 (.061 ± .004)

.050R TYP.

Top Cover Tape

User Direction of Feed

Rev. X



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